

TO-CAN Based Tunable Laser Optical Sub-Assembly

TOSA TLCBD



Key Features

- **Up to 16 channels at 100 GHz spacing or up to 32 channels at 50GHz spacing**
- **C- or L-band**
- **Simple tuning algorithm**
- **2.5 Gbps direct modulation**
- **Low-cost TO-can based optical subassembly**

Applications

- **NGPON2**
- **WDM-PON**
- **Optical interconnects**
- **DWDM sparing**

Widely wavelength tunable semiconductor lasers are key components for next-generation optical networks. Conventional tunable lasers require complex fabrication processes such as non-uniform gratings and multiple epitaxial growths, and need multiple electrodes with complex control algorithms for wavelength tuning. As the dense wavelength division multiplexing (DWDM) technology extends towards access and data center networks, the cost reduction and operational simplicity have become more and more important.

We have developed a simple and compact tunable laser based on patented proprietary technologies. It consists of a half-wave coupled V-cavity laser with only three electrodes: one for gain and direct modulation, one for channel selection corresponding to the ITU grid, and the third for fine tuning when needed. The laser structure does not involve any grating or epitaxial regrowth, and has a size of only about $500\mu\text{m} \times 300\mu\text{m}$. The advantages of compactness, fabrication simplicity and easy wavelength control offer cost-effective tunable laser solutions for many applications in access and data center networks, and beyond.

This series Transmitter Optical Sub-Assembly (TOSA) is based on an 8-pin TO-CAN package that offers further cost reduction compared to our previously released TLDX15 series tunable TOSA. It comprises a V-cavity edge-emitting tunable laser, a power monitoring photodiode, an isolator, and a TEC controller, with an LC connector. Currently it can provide up to 16 channels at 100GHz spacing or 32 channels at 50GHz spacing in C- or L- band (other wavelength bands available on request), with a customer specified starting wavelength. The laser chip can be operated in semi-cooled condition at 40-60°C while the ambient operating temperature is between 0 and 70°C.

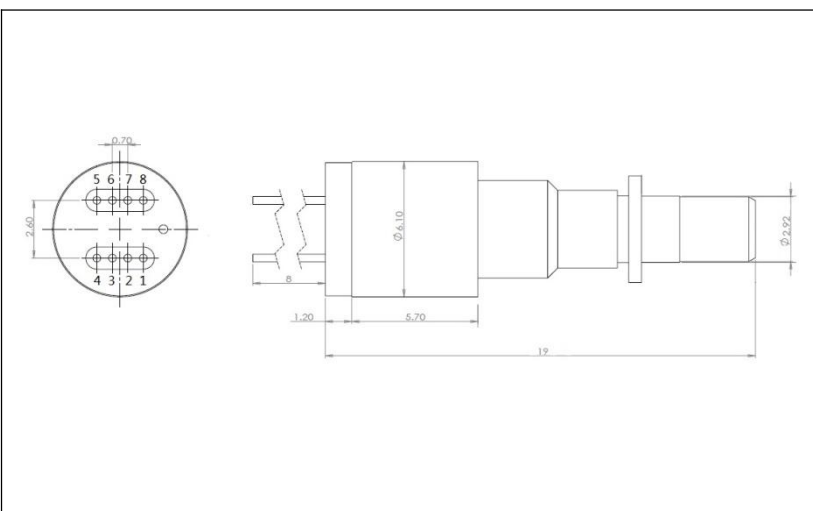
Specifications

Parameters	Min.	Typ.	Max.	Unit
Optical Output Power	≥ 0			dBm
Ambient Operating Temperature	0	-	70	°C
Gain Forward Bias Current	25	30	50	mA
Channel Selector Current	20	-	100	mA
Fine Tuning Current	20	25	40	mA
LD Forward Bias Voltage	-	-	2.3	V
Modulation Data Rate	2.5 (higher data rates under development)			Gbps
Wavelength	C- or L-band (other wavelengths available on request)			
Channel Spacing	50 or 100			GHz
Number of Channels	Up to 16@100GHz, or 32@50GHz			
Side Mode Suppression Ratio	35	38-40	-	dB
Optical Isolation	25	-	-	dB
Relative Intensity Noise	-	-	-135	dB/Hz
Power Monitor Current	20	-	500	μA
Power Monitor Dark Current	-	-	100	nA
TEC Current	-	0.5	0.9	A
TEC Voltage	-	-	1.2	V
Total Power Consumption (P _{LD} + P _{TEC})	-	0.8	1.5	W
Thermistor B constant	-	4050	-	K
Thermistor Resistance @25°C	9.5	10	10.5	kΩ

* Product specifications are subject to change without notice.

Dimensions

(in millimeters)



Pin Assignments

Pin	Symbol	Description
1	TEC+	TEC anode
2	R _{th}	Thermistor
3	LD3+	Fine tuning
4	PD-	PD cathode
5	LD1+	Gain bias and modulation signal
6	Common	LD3-/LD1-/PD+/L D2-/R _{th}
7	LD2+	Channel selector
8	TEC-	TEC cathode